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(71) Applicant (for all designated States except US):
ATOTECH DEUTSCHLAND GMBH [DE/DE];
Erasmusstrasse 20, 10553 Berlin (DE).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **HÜBEL, Egon**
[DE/DE]; Altdorfer Strasse 35, 90537 Feucht (DE).

(74) Agent: **EFFERT, BRESSEL UND KOLLEGEN**;
Radickestrasse 48, 12489 Berlin (DE).

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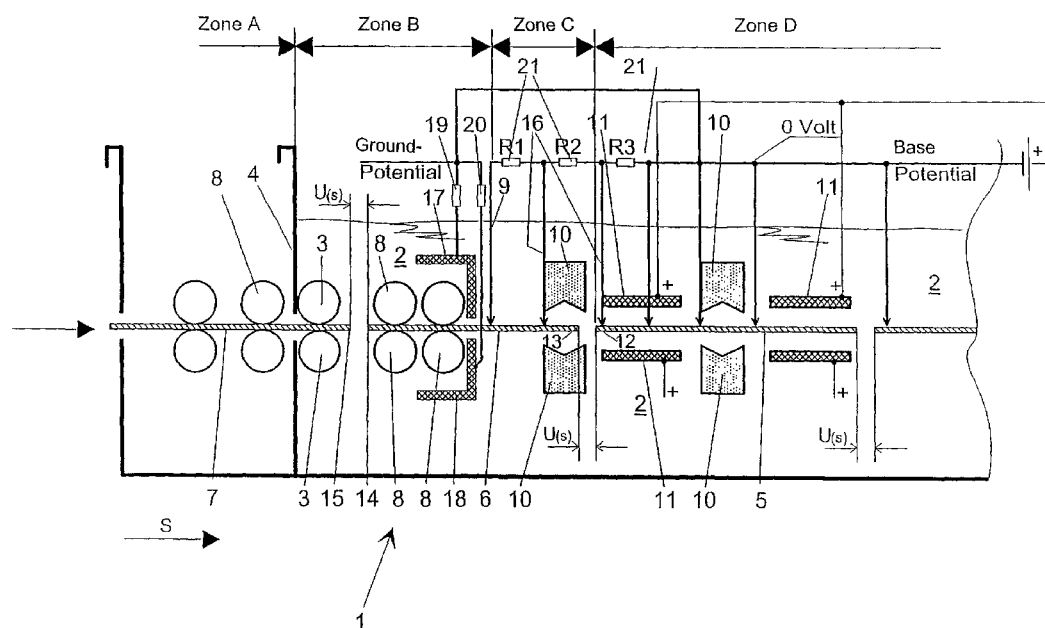
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(54) Title: CONVEYORIZED PLATING LINE AND METHOD FOR ELECTROLYTICALLY METAL PLATING A WORK-PIECE



(57) Abstract: To avoid voids in the metal layer in holes of printed circuit boards, a conveyORIZED plating line and a method for electrolytically metal plating printed circuit boards are proposed which provide measures for reducing an electric voltage that builds up between adjacent printed circuit boards being conveyed through the line.



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